



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT

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2/4/03

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Signature

Applicant : Kurt G. Steiner, et al.
Application No. : 10/038,352
Filed : January 2, 2002
Title : STRUCTURE AND METHOD FOR ISOLATING POROUS
LOW-K DIELECTRIC FILMS

Grp./Div. : 2812
Examiner : H.T. Nguyen

Docket No. : 47071/MJM/A717

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RESPONSE TO OFFICE ACTION DATED OCTOBER 23, 2002

Assistant Commissioner for Patents
Washington, D.C. 20231

Post Office Box 7068
Pasadena, CA 91109-7068
January 23, 2003

Commissioner:

In response to the Office action dated October 23, 2002, please amend the above-identified application as follows and re-examine and reconsider the application in view of the amendments and remarks provided.

AMENDMENTS

In the Claims:

Please cancel claims 3 and 18-25 and amend claims 1, 4, 6, 8, 9 and 13 as indicated in the attached Version with Markings to Show Changes Made. Please add new claims 26 and 27. The complete set of pending claims 1, 2, 4-17, 26 and 27, in amended version, is as follows: